PRODUCT / PROCESS CHANGE NOTIFICATION

Notification Date: 12/28/2009 **Projected Completion Date: 3/1/2010** **PCN Number : 10179**

Product Identification (Including Customer P/N):
See attached list

Detailed Description of Changes:
Switched integrated circuits packaging vendor.

Reason for Changes:
Integrated circuits packaging vendor stopped assembling this die.

Projected Timing of Change and Implementation Date:
Immediate

Anticipated Impact on Quality and Reliability:
No degradation of quality is anticipated.

Qualification Plan (if applicable):
HTOL 1008hrs at 125°C (JESD22-A-108-B), Temperature Cycle -55°C to 125°C, 1000 Cycles (JESD22-A-104B), Solder reflow 260°C/10seconds

Last Time Buy Date:
Can not buy, as the raw material from our current packaging vendor is depleted.

Last Time Delivery Date and Comments (if applicable):
Last time delivery date has passed.

Originated By:	Kent Buckman	**Date:**	12/23/2009
MtronPTI Engineering:	Joe Doyle	**Date:**	1/11/2010
MtronPTI Apps. Eng'r.:	Bill Jannewein	**Date:**	1/18/2010
MtronPTI Sales or Designate:	Dick Thompson	**Date:**	1/18/2010
MtronPTI Operations:	Ganderson	**Date:**	11/10/2009
MtronPTI Quality Assurance:	JKocak	**Date:**	1/11/2010

CUSTOMER ACKNOWLEDGMENT:
This PCN will be considered acceptable and become effective on the date shown if no feedback is received within 30 days of notification denoted above.

PCN APPROVED: **Signature:** _____

YES: [ ] **NO:** [ ] **Title:** _____ **Date:** _____

COMMENTS:

Please return this signed document to:
MtronPTI, 100 Douglas Ave., Yankton, SD, 57078 or email to pcn@mtronpti.com